



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: Double Data Rate (DDR) 3

Stack Height: 5.2 mm [.205 in]

Module Orientation: Right Angle

Number of Positions: 204

Centerline (Pitch): .6 mm [.024 in]

Features

Product Type Features

Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 3

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	204

Electrical Characteristics

DRAM Voltage	1.5 V
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Signal Characteristics

SGRAM Voltage	1.5 V
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Body Features

Ejector Location	Both Ends
Latch Material	Stainless Steel
Latch Plating Material	Tin
Module Key Type	SGRAM
Ejector Type	Locking
Connector Profile	Reverse

Contact Features

Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold Flash

Termination Features

Insertion Style	Cam-In
Termination Method to Printed Circuit Board	Surface Mount

Mechanical Attachment

Mating Alignment Type	Reverse Keying
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm[.024 in]

Dimensions

Stack Height	5.2 mm[.205 in]
Row-to-Row Spacing	8.2 mm[.322 in]

Usage Conditions

Operating Temperature Range	-55 - 85 °C[-67 - 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	200
Packaging Method	Emboss on Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 2309407-1
DDR4 SODIMM 260P 4.0H STD

Also in the Series

RAYCHEM RVS

Joins & Splices(4)

RJ45 Connectors(1)

SD Card Connectors(2)

SO DIMM Sockets(13)

Customers Also Bought

TE Part # 1-338311-2
25POS.HD20 PLUG ASS

TE Part # 1857994-1
Z-PACK/A F-HDR 110P, EON

TE Part # 2198325-6
zSFP+ STACKED 2X2 RECEPTACLE ASSEMBLY

TE Part # 2-2013022-1
EMBOSS TAPE DDR3 204P 4H STD

TE Part # 5223961-1
TE UPM R/A Header 3P STD Power, LLL

TE Part # 3-6318490-6
.5FHR04H,220,S,GIG,08/Sn,HT,NSYes

TE Part # 8-1879336-4
CPF 0603 1K69 1% 50PPM 1K RL

TE Part # 2309412-3
DDR4 SODIMM 260P 8.0H RVS

TE Part # 244837-E
SMCQ 26 M AB VV 8-13 CL * H007 137 E005

TE Part # 1717831-1
MINI PCI EXPRESS SEMI HARD TRAY CONN



Documents

Product Drawings
EMBOSS TAPE DDR3 204P 5.2H RVS

English

CAD Files

3D PDF

3D

Customer View Model
ENG_CVM_CVM_2-2013290-1_B_c-2-2013290-1-b.2d_dxf.zip

English

Customer View Model
ENG_CVM_CVM_2-2013290-1_B_c-2-2013290-1-b.3d_igs.zip

English

Customer View Model
ENG_CVM_CVM_2-2013290-1_B_c-2-2013290-1-b.3d_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages
DDR3 DIMM Sockets Flyer 6-1773454-7 05/09

English

Product Specifications
Product Specification

English